

ASMNUT.001A



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Uzoh et al.  
App. No. : 10/769,605  
Filed : January 30, 2004  
For : METHOD OF  
ELECTROPLATING COPPER  
LAYERS WITH FLAT  
TOPOGRAPHY  
Examiner : William T. Leader

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

July 29, 2005

(Date)

Tina Chen, Reg. No. 44,606

STATUS LETTER

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Our file for the above-identified application reveals that there has been no action taken since the application was filed, i.e. January 30, 2004. Please inform us as to the status of this application.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: July 29, 2005

By: 

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